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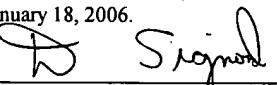
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Chuen Rong Leu et al.
Assignee: Bridge Semiconductor Corporation
Title: METHOD OF MAKING A SEMICONDUCTOR CHIP ASSEMBLY WITH AN EMBEDDED METAL PILLAR
Serial No.: 10/719,823 Filed: November 21, 2003
Examiner: Unknown Group Art Unit: 2812
Atty. Docket No.: BDG024-1

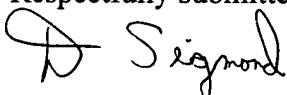
COMMISSIONER FOR PATENTS
P.O. Box 1450
Alexandria, VA 22313

TRANSMITTAL OF FORMAL DRAWINGS

Attached please find the formal drawings (36 sheets) for this application.

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on January 18, 2006.	
 _____ David M. Sigmond Attorney for Applicant	1/18/06 _____ Date of Signature

Respectfully submitted,



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